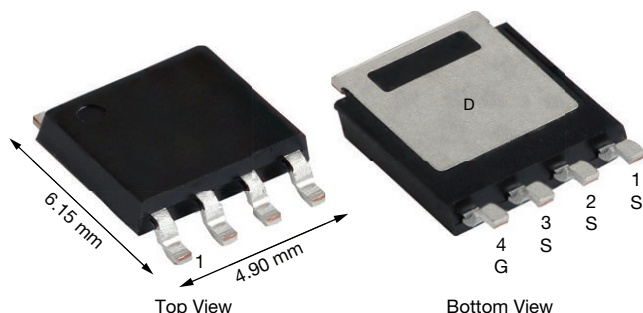
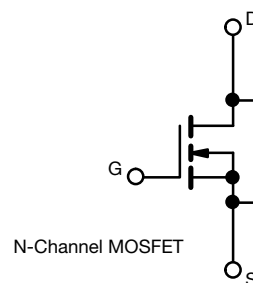


Automotive N-Channel 100 V (D-S) 175 °C MOSFET

PowerPAK® SO-8L


FEATURES

- TrenchFET® Gen IV power MOSFET
- AEC-Q101 qualified
- 100 % R_g and UIS tested
- Q_{gd}/Q_{gs} ratio < 1 optimizes switching characteristics
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT
HALOGEN
FREE


PRODUCT SUMMARY	
V_{DS} (V)	100
$R_{DS(on)}$ (Ω) at $V_{GS} = 10$ V	0.0197
I_D (A) ^e	38
Configuration	Single
Package	PowerPAK SO-8L

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJ118EP (for detailed order number please see www.vishay.com/doc?79776)

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V_{DS}	100	V
Gate-source voltage		V_{GS}	± 20	
Continuous drain current ^e	$T_C = 25$ °C	I_D	38	A
	$T_C = 125$ °C		22	
Continuous source current (diode conduction) ^e		I_S	50	
Pulsed drain current ^{b, e}		I_{DM}	84	
Single pulse avalanche current		I_{AS}	22	
Single pulse avalanche energy		E_{AS}	24	mJ
Maximum power dissipation ^{b, e}	$T_C = 25$ °C	P_D	500	W
	$T_C = 125$ °C		166	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) ^c			260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount ^a	R _{thJA}	42	°C/W
Junction-to-case (drain) ^d		R _{thJC}	2	

Notes

- Pulse test; pulse width ≤ 300 μ s, duty cycle ≤ 2 %
- When mounted on 1" square PCB (FR4 material)
- See solder profile (www.vishay.com/doc?73257). The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- As per JESD51-14
- Values based on R_{thJC} and T_C of 25 °C. Actual values achievable will be dependent on the thermal characteristics of the complete system



SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0, I _D = 250 μA		100	-	-	V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.0	2.7	3.5	
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V		-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 80 V	-	-	10	μA
		V _{GS} = 0 V	V _{DS} = 80 V, T _J = 125 °C	-	-	50	
		V _{GS} = 0 V	V _{DS} = 80 V, T _J = 175 °C	-	-	250	
On-state drain current ^a	I _{D(on)}	V _{GS} = 10 V	V _{DS} ≥ 5 V	30	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 15 A	-	0.0164	0.0197	Ω
		V _{GS} = 10 V	I _D = 15 A, T _J = 125 °C	-	-	0.0405	
		V _{GS} = 10 V	I _D = 15 A, T _J = 175 °C	-	-	0.0510	
Forward transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 20 A		-	60	-	S
Dynamic ^b							
Input capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = 25 V, f = 1 MHz	-	2073	2903	pF
Output capacitance	C _{oss}			-	230	322	
Reverse transfer capacitance	C _{rss}			-	8	12	
Total gate charge ^c	Q _g	V _{GS} = 10 V	V _{DS} = 50 V, I _D = 6 A	-	31	47	nC
Gate-source charge ^c	Q _{gs}			-	9	-	
Gate-drain charge ^c	Q _{gd}			-	7	-	
Gate resistance	R _g	f = 1 MHz		0.6	1.2	1.8	Ω
Turn-on delay time ^c	t _{d(on)}	V _{DD} = 50 V, R _L = 8.33 Ω I _D ≅ 6 A, V _{GEN} = 10 V, R _g = 1 Ω		-	12	18	ns
Rise time ^c	t _r			-	3	6	
Turn-off delay time ^c	t _{d(off)}			-	22	33	
Fall time ^c	t _f			-	4	8	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed current ^a	I _{SM}			-	-	84	A
Forward voltage	V _{SD}	I _F = 15 A, V _{GS} = 0 V		-	-	1.1	V
Body diode reverse recovery time	t _{rr}	I _F = 5 A, di/dt = 100 A/μs		-	38	76	ns
Body diode reverse recovery charge	Q _{rr}			-	54	108	nC
Reverse recovery fall time	t _a			-	29	-	ns
Reverse recovery rise time	t _b			-	9	-	
Body diode peak reverse recovery current	I _{RM(REC)}			-	-2.4	-	A

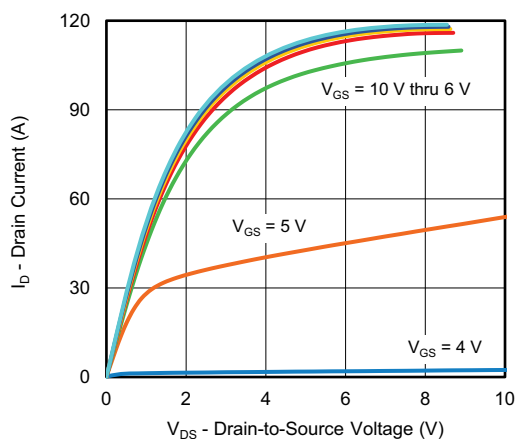
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing
c. Independent of operating temperature

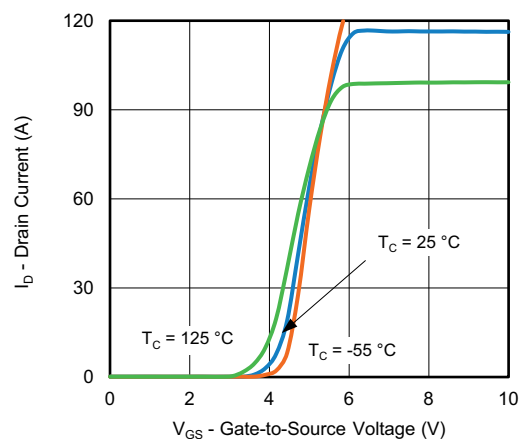
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



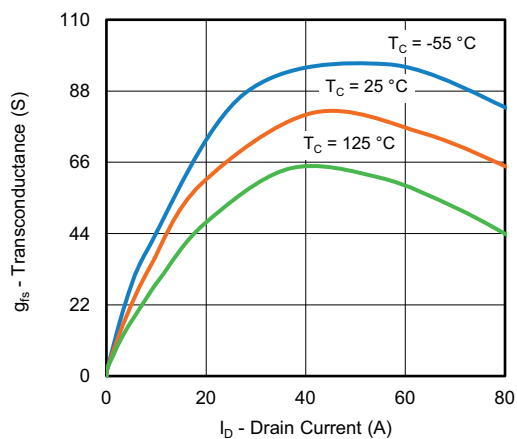
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



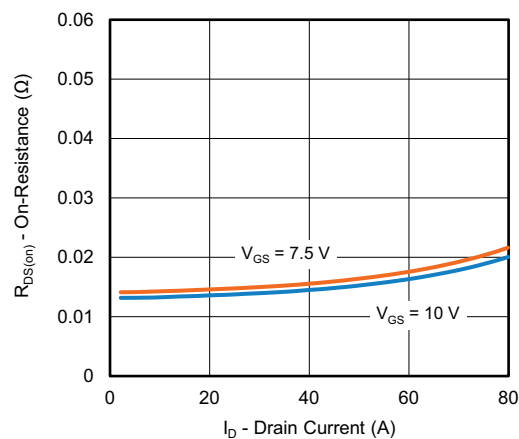
Output Characteristics



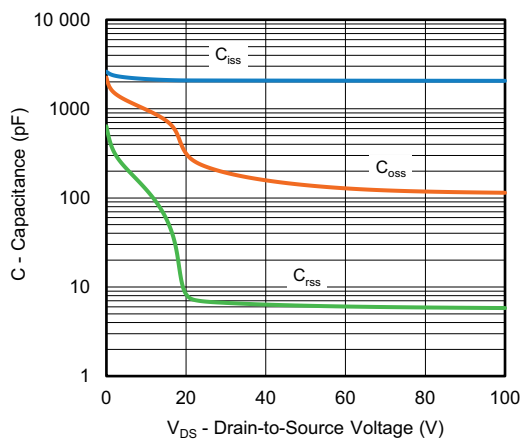
Transfer Characteristics



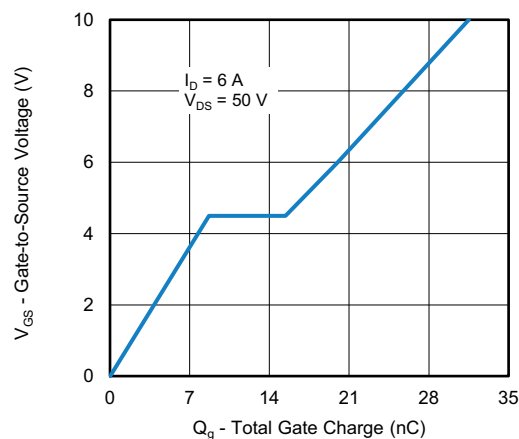
Transconductance



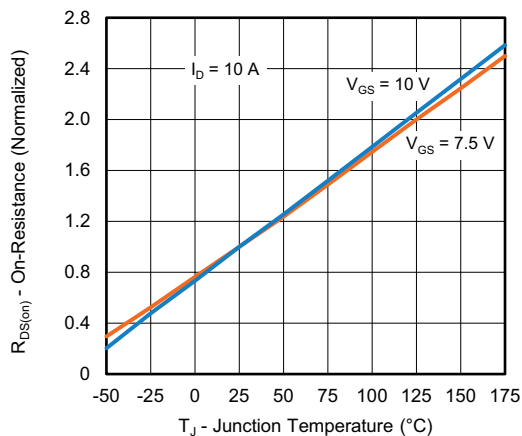
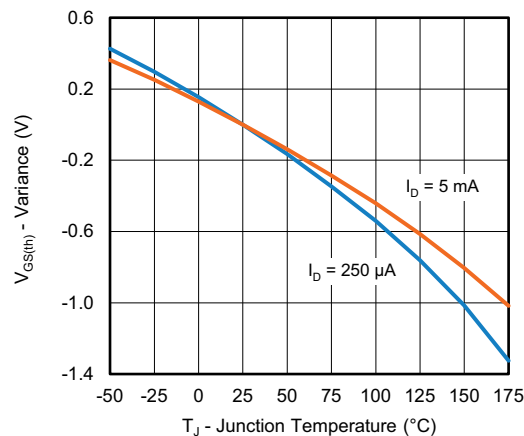
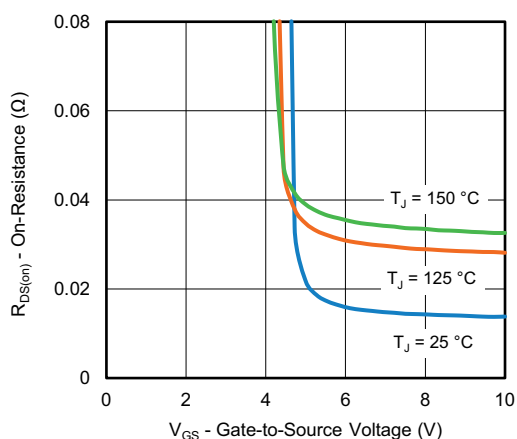
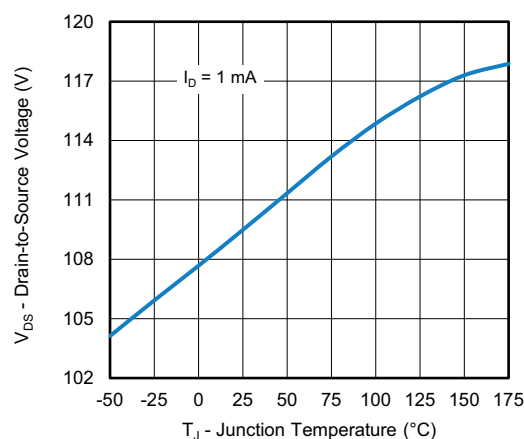
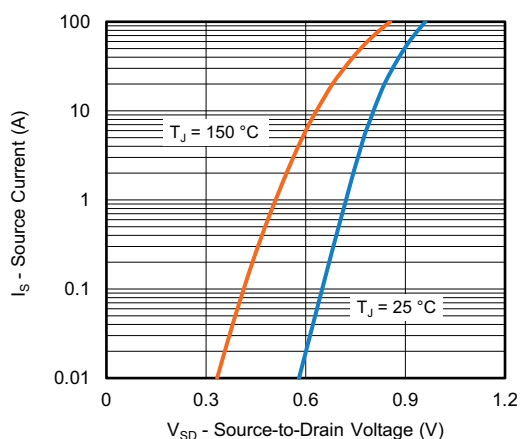
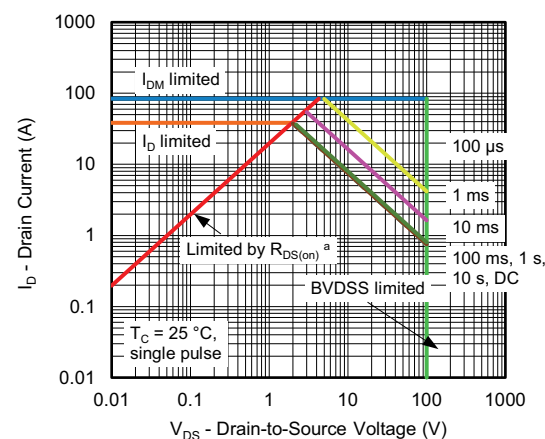
On-Resistance vs. Drain Current



Capacitance

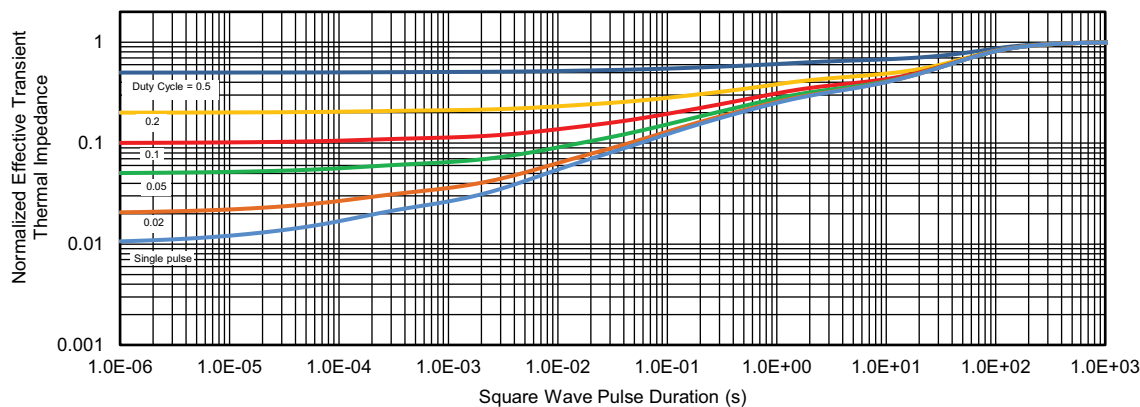


Gate Charge

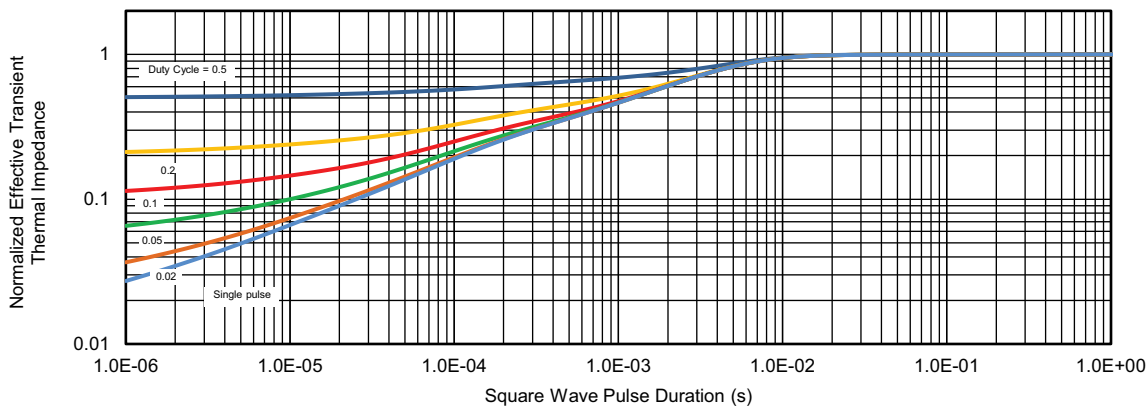
**TYPICAL CHARACTERISTICS** ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)**On-Resistance vs. Junction Temperature****Threshold Voltage****On-Resistance vs. Gate-to Source Voltage****Drain Source Breakdown vs. Junction Temperature****Source Drain Diode Forward Voltage****Safe Operating Area****Note**a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^{\circ}\text{C}$)are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

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